

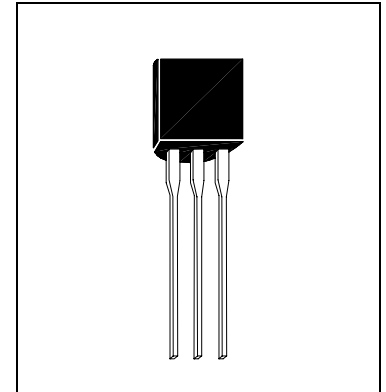


# HMP5A26

NPN SILICON TRANSISTOR

## Description

The HMP5A26 is designed for using in darlington transistor.



## Absolute Maximum Ratings

- Maximum Temperatures  
 Storage Temperature ..... -55 ~ +150 °C  
 Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation  
 Total Power Dissipation (Ta=25°C) ..... 625 mW
- Maximum Voltages and Currents (Ta=25°C)  
 VCBO Collector to Base Voltage ..... 50 V  
 VCES Collector to Emitter Voltage..... 50 V  
 VEBO Emitter to BASE Voltage ..... 10 V  
 IC Collector Current ..... 500 mA

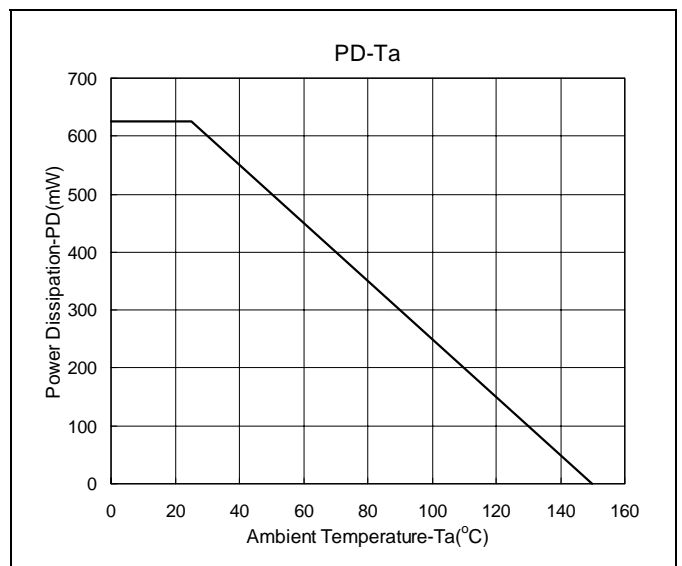
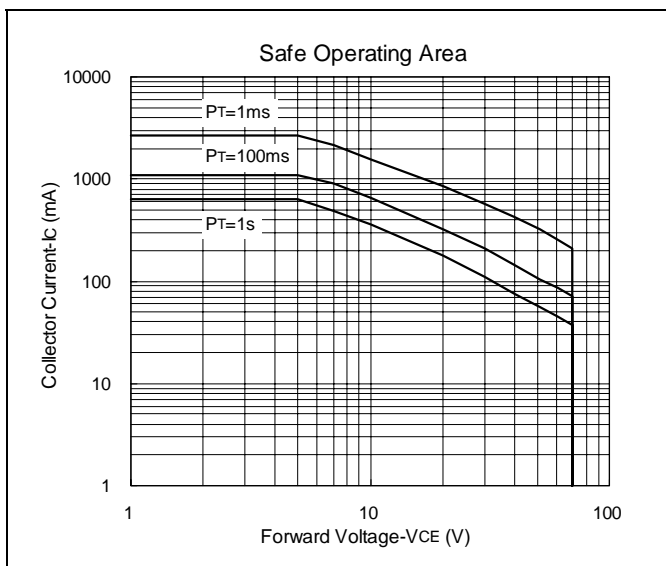
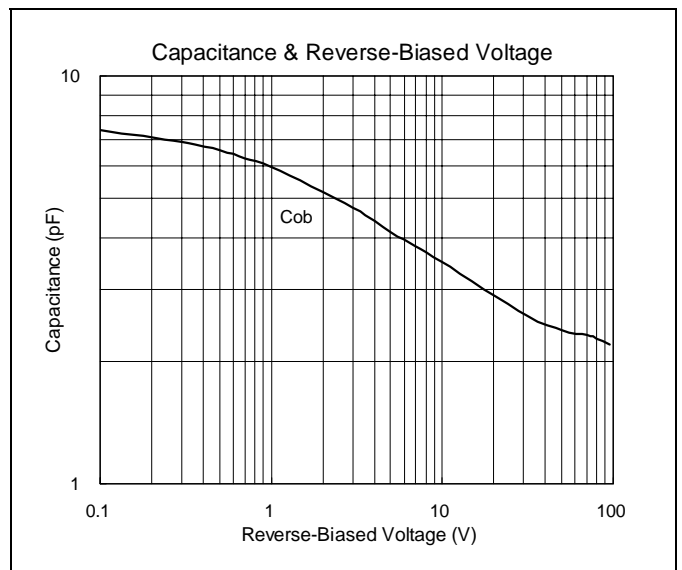
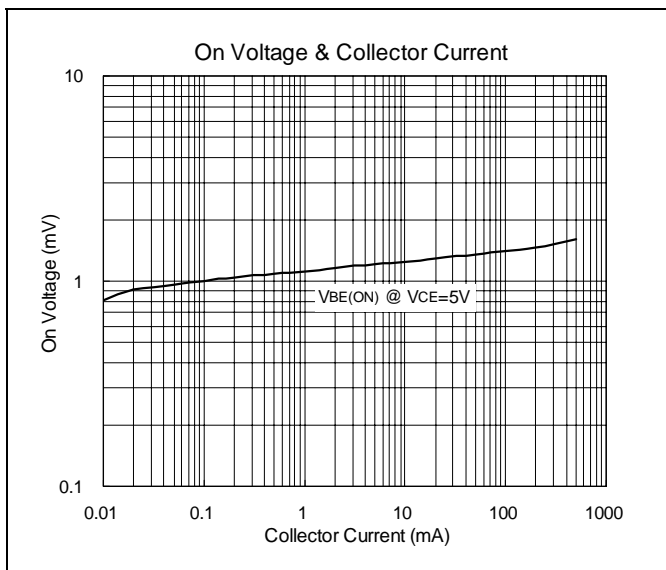
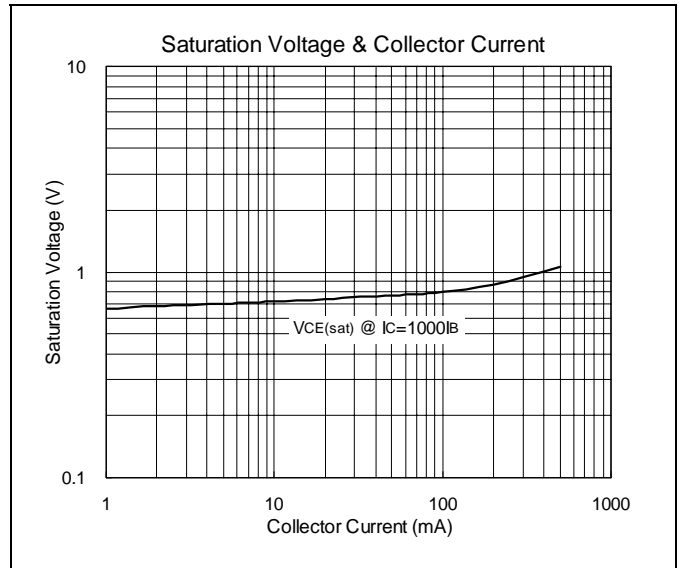
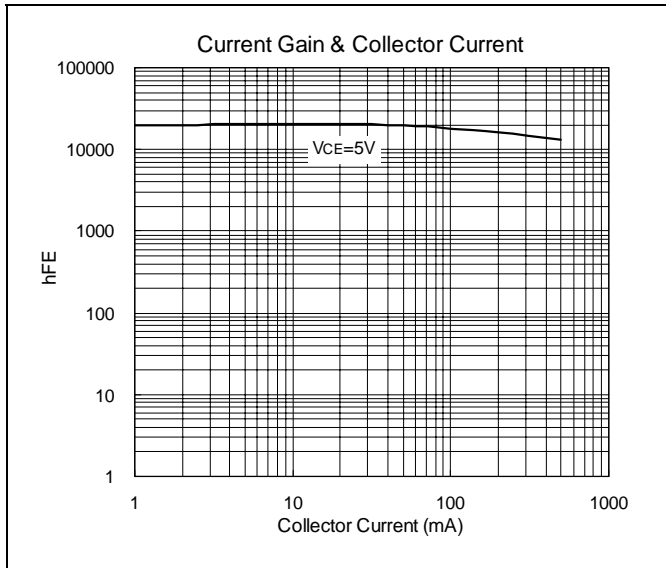
## Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	50	-	-	V	IC=100uA, IE=0
BVCES	50	-	-	V	IC=100uA, VBE=0
BVEBO	10	-	-	V	IE=10uA, IC=0
ICBO	-	-	100	nA	VCB=40V, IE=0
ICES	-	-	500	nA	VCE=40V, VBE=0
IEBO	-	-	100	nA	VEB=10V, IC=0
*VCE(sat)	-	-	1.5	V	IC=100mA, IB=100uA
VBE(on)	-	0.6	2	V	VCE=5V, IC=100mA
*hFE1	10K	-	-		VCE=5V, IC=10mA
*hFE2	10K	-	-		VCE=5V, IC=100mA

\*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



### Characteristics Curve





### TO-92 Dimension

3-Lead TO-92 Plastic Package  
HSMC Package Code : A

**Marking :**

HSMC Logo → □ □ □ □ ← Product Series  
 Part Number → □ □ □ □ □ □  
 Date Code → □ □ □ □ □ □ ← Rank  
 Laser Mark

HSMC Logo  
 Product Series  
 Part Number → □ □ □ □ □ □  
 Ink Mark

Style : Pin 1. Emitter 2. Base 3. Collector

\*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

**Notes :** 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.  
 2.Controlling dimension : millimeters.  
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material :**

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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